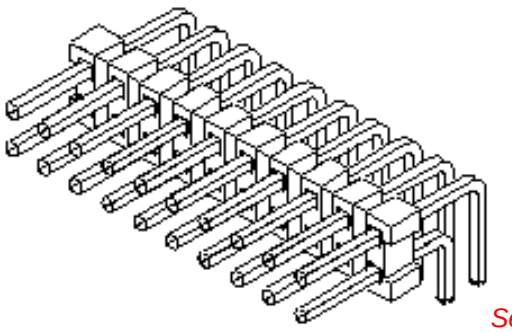
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This document was generated on 03/30/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: 0717640210
Status: Active
Description: 2.54mm (.100") Pitch C-Grid® Breakaway Header, Low Profile, Dual Row, Right Angle, High Temperature, 10 Circuits, 0.76µm (30µ") Gold (Au) Selective Plating



Series image - Reference only

Documents:

3D Model
Drawing (PDF)
Packaging Specification (PDF)
Product Specification PS-71764 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	PCB Headers
Series	71764
Application	Board-to-Board, Wire-to-Board
Product Name	C-Grid®

Physical

Breakaway	Yes
Circuits (Loaded)	10
Circuits (maximum)	10
Color - Resin	Black
Durability (mating cycles max)	50
Flammability	94V-0
Glow-Wire Compliant	No
Lock to Mating Part	None
Material - Metal	Brass, Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Rows	2
Orientation	Right Angle
PC Tail Length (in)	0.110 In
PC Tail Length (mm)	2.79 mm
PCB Locator	No
PCB Retention	None
Packaging Type	Tube
Pitch - Mating Interface (in)	0.100 In
Pitch - Mating Interface (mm)	2.54 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	75
Plating min: Termination (µm)	1.875
Polarized to Mating Part	No
Shrouded	No
Stackable	Yes
Temperature Range - Operating	-40°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	3A
Voltage - Maximum	250V

Solder Process Data

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
71764Series

Lead-free Process Capability	SMC & Wave Capable (TH only)
Process Temperature max. C	260

Material Info

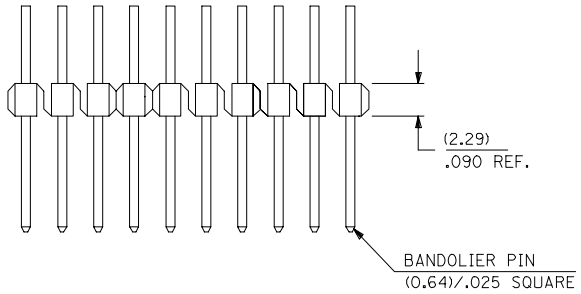
Reference - Drawing Numbers

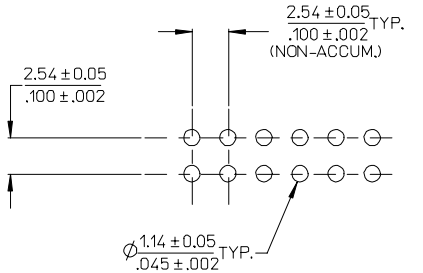
Product Specification	PS-71764
Sales Drawing	SD-71764-001

This document was generated on 03/30/2010

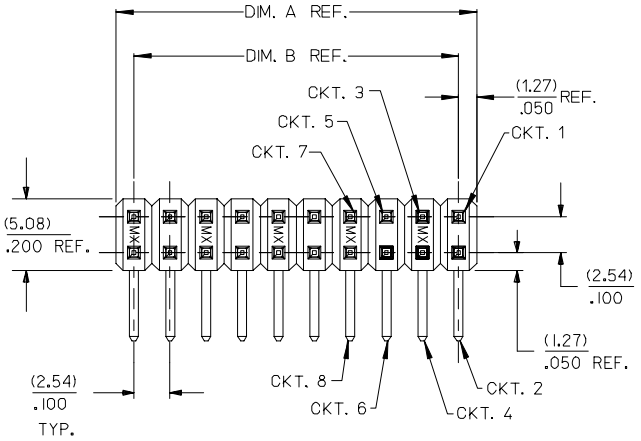
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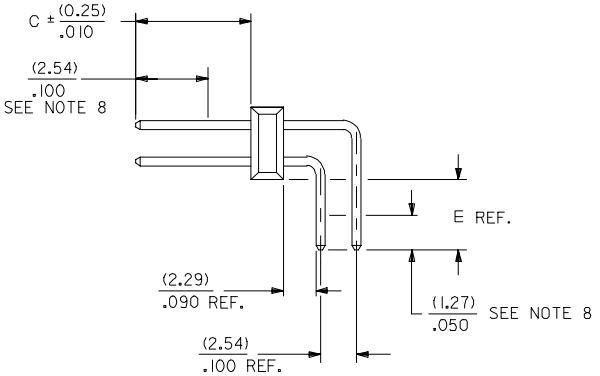
CKTS	DIM. A	DIM. B
04	(5.08)/.200	(2.54)/.100
06	(7.62)/.300	(5.08)/.200
08	(10.16)/.400	(7.62)/.300
10	(12.70)/.500	(10.16)/.400
12	(15.24)/.600	(12.70)/.500
14	(17.78)/.700	(15.24)/.600
16	(20.32)/.800	(17.78)/.700
18	(22.36)/.900	(20.32)/.800
20	(25.40)/1.000	(22.36)/.900
22	(27.94)/1.100	(25.40)/1.000
24	(30.48)/1.200	(27.94)/1.100
26	(33.02)/1.300	(30.48)/1.200
28	(35.56)/1.400	(33.02)/1.300
30	(38.10)/1.500	(35.56)/1.400





RECOMMENDED P.C. BOARD HOLE LAYOUT





NOTES:
1. MATERIAL: WAFER - HIGH TEMPERAURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
   PIN - COPPER ALLOY
2. PLATING:
   TIN - (0.00381)/.000150 MINIMUM TIN PLATE
   OVER NICKEL PLATE.
   15 GOLD - (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA,
   (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
   OVER NICKEL PLATE OVERALL.
   30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA,
   (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
   OVER NICKEL PLATE OVERALL.
   * THE PRIMARY SHPPING CARTON WILL BE LABELD 'COMPLIANT TO
   RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'.
   CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
3. PRODUCT CONFORMS TO PS-71764.
4. PACKAGING INFORMATION:
   FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
   FOR 10 CIRCUITS AND OVER USE PK-70873-0075
5. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
6. PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE
   PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE.
   (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
7. WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
8. MEASURE POINT FOR PLATING THICKNESS.
9. THIS PART CONFORMS TO CLASS B REQUIREMENTS
   OF COSMETIC SPECIFICATION PS-45499-002

2	A
1	A1
SHT.	REV.

ADD NOTE 9 2006/12/11
EC NO: UCP2007-1441 2006/12/11
DRWN:PRIDDER CHKD:ADERR 2006/12/12
APPR:FSMITH DESCRIPTION
REV A1

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± .01
2 PLACES	± 0.25	± .01
1 PLACE	± 0.25	± ---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: CAC DATE: 1995/08/23
CHECKED BY: PR DATE: 1995/08/23
APPROVED BY: DJB DATE: 1995/08/23

TITLE: DUAL ROW WAFER ASS'Y W/BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-71764-001
SHEET NO.: 1 OF *

SIZE C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

ITEM NO: 71764-0004/0030, 9003		
DIM. C	(6.10)/.240	
DIM. E (REF.)	(2.79)/.110	
FINISH	TIN	
CONNECTOR END PLATING	TIN	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0004	
06	71764-0006	
08	71764-0008	
10	71764-0010	
12	71764-0012	
14	71764-0014	
16	71764-0016	
18	71764-0018	
20	71764-0020	
22	71764-0022	
24	71764-0024	
26	71764-0026	
28	71764-0028	
30	71764-0030	
06	71764-9003	3

ITEM NO: 71764-0104/0130, 9001, 9004		
DIM. C	(6.10)/.240	
DIM. E (REF.)	(2.79)/.110	
FINISH	15 GOLD	
CONNECTOR END PLATING	GOLD	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0104	
06	71764-0106	
08	71764-0108	
10	71764-0110	
12	71764-0112	
14	71764-0114	
16	71764-0116	
18	71764-0118	
20	71764-0120	
22	71764-0122	
24	71764-0124	
26	71764-0126	
28	71764-0128	
30	71764-0130	
06	71764-9001	3, 4
08	71764-9004	5, 6

ITEM NO: 71764-0204/0230, 9000, 9002		
DIM. C	(6.10)/.240	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	30 GOLD	
CONNECTOR END PLATING	GOLD	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0204	
06	71764-0206	
08	71764-0208	
10	71764-0210	
12	71764-0212	
14	71764-0214	
16	71764-0216	
18	71764-0218	
20	71764-0220	
22	71764-0222	
24	71764-0224	
26	71764-0226	
28	71764-0228	
30	71764-0230	
06	71764-9002	3, 4
10	71764-9000	8

REV:	ECR/ECN INFORMATION	TITLE:	SHEET No.
A	EC No: **UCP2007-0449** DATE: **2006-08-18**	DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	**- 2 -**

DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
SD-71764-001	**PRIDDER**	**ADERR**	**FSMITH**

ITEM NO: 71764-0304/0330		
DIM. C	(8.13)/.320	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	TIN	
CONNECTOR END PLATING	TIN	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0304	
06	71764-0306	
08	71764-0308	
10	71764-0310	
12	71764-0312	
14	71764-0314	
16	71764-0316	
18	71764-0318	
20	71764-0320	
22	71764-0322	
24	71764-0324	
26	71764-0326	
28	71764-0328	
30	71764-0330	

ITEM NO: 71764-0404/0430		
DIM. C	(8.13)/.320	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	15 GOLD	
CONNECTOR END PLATING	GOLD	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0404	
06	71764-0406	
08	71764-0408	
10	71764-0410	
12	71764-0412	
14	71764-0414	
16	71764-0416	
18	71764-0418	
20	71764-0420	
22	71764-0422	
24	71764-0424	
26	71764-0426	
28	71764-0428	
30	71764-0430	

ITEM NO: 71764-0504/0530		
DIM. C	(8.13)/.320	
DIM. E (REF.)	(2.79)/.110	
PLATING FINISH	30 GOLD	
CONNECTOR END PLATING	GOLD	
P.C. BOARD END PLATING	TIN	
PACKAGING	SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS
04	71764-0504	
06	71764-0506	
08	71764-0508	
10	71764-0510	
12	71764-0512	
14	71764-0514	
16	71764-0516	
18	71764-0518	
20	71764-0520	
22	71764-0522	
24	71764-0524	
26	71764-0526	
28	71764-0528	
30	71764-0530	

REV:	ECR/ECN INFORMATION	TITLE:	SHEET No.
A	EC No: **UCP2007-0449** DATE: **2006-08-18**	DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	**- 3 -**

DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
SD-71764-001	**PRIDDER**	**ADERR**	**FSMITH**